

Features

- 2.15×2.40mm with 1.80mm lens
- High Brightness
- Water Clear
- Small double-end package
- EIA Std. package
- Mono-color type
- Special packaging available upon request
- High reliability

Applications

- PCB mounted infrared sensor
- Infrared emitting for miniature light barrier
- Floppy disk drive
- Optoelectronic switch
- Smoke detector

Description

The INA-912AHIR25 is high brightness SMD Axial LED. It is a 1.8mm Lens type LED which can be used in various applications.

Recommended Solder Pattern



Figure 1. INA-912AHIR25 Solder Pattern



Package Dimensions in mm

Figure 2. INA-912AHIR25 Package Dimensions

Notes

- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is \pm 0.25 mm (.010") unless otherwise noted.



Absolute Maximum Rating at 25°C (Note)

Product	Emission Color	P _d (mW)	l _F (mA)	I _{FP} * (A)	V _R (V)	T₀₽ (°C)	Tst (°C)
INA-912AHIR25	Infrared	90	50	1.00	5	-40°C~+80°C	-40°C~+85°C

Notes

1. Derate linearly as shown in derating curve.

2. Duty Factor = 10%, Frequency = 1 kHz

Electrical Characteristics T_A = 25°C (Note)

Product	Emission Color	l⊧(mA)	V _F (V)				λ(nm)		Viewing Angle	Ee (r		mW/sr)						
			IF	IF=20mA IF=100mA, tp=100µs, tp/T=0.01		λD	λP	Δλ	201/2	IF=20mA		IF=100mA, tp=100µs, tp/T=0.01						
INA-912AHIR25	Infrared	20	min	typ	max	min	typ	max		- 940	50	25	min	typ	max	min	typ	max
			0.8	1.2	1.5	-	1.6	1.8	-				3	6	-	-	15	-

Notes

1. Performance guaranteed only under conditions listed in above tables.

2. A luminous intensity is measured with a light sensor and filter combination that approximates the CIE eye-response curve.

3. 201/2 is the o -axis angle where the luminous intensity is 1/2 the peak intensity.

 The dominant wavelength (λd) is derived from the CIE chromaticity diagram and represents the single wavelength which defines the color of the device.

ESD Precaution

ATTENTION: Electrostatic Discharge (ESD) protection



The symbol above denotes that ESD precaution is needed. ESD protection for GaP and AlGaAs based chips is necessary even though they are relatively safe in the presence of low static-electric discharge. Parts built with AlInGaP, GaN, or/and InGaN based chips are STATIC SENSITIVE devices. ESD precaution must be taken during design and assembly. If manual work or processing is needed, please ensure the device is adequately protected from ESD during the process.

Please be advised that normal static precautions should be taken in the handling and assembly of this device to prevent damage or degradation which may be induced by electrostatic discharge (ESD).



Typical Characteristic Curves Infrared



Peak Emission Wavelength & Ambient Temperature



Forward Current & Forward Voltage



Forward Current & Ambient Temperature











Relative Intensity & Forward Current

Relative Radiant Intensity & Angular Displacement





Ordering Information

Product	Emission Color	Test Current I⊧ (mA)	Radiant Intensity Ee (mW/sr) (Typ.)		Ee (mW/sr) VF (V) Part Num		Orderable Part Number
	Infrared	20	IF=20mA	IF=100mA, tp=100µs, tp/T=0.01	IF=20mA	IF=100mA, tp=100µs, tp/T=0.01	INA-912AHIR25
INA-912AHIR25			6	15	1.2	1.6	ΙΝΑ-9ΙΖΑΠΙΚΖΟ

Label Specifications





Inolux P/N:

Ι	Ν	А	-	912	А		HIR	25	Х	Х	Х	Х	
				Package		Lens	Color	View Angle	Customized Stamp-off				
	Inolu ad fra Axia	me		912/ Lead f Axi	rame	(Blank) = Clear Lens	HIR = 940nm	25 = 25 deg.					

Lot No.:

Z	2	0	1	7	01	24	001
Internal Tracker		Year (2017,	, 2018,)		Month	Date	Serial



Reliability

Item		Standards	Conditions				
	failures	Reference	1) Delvie a et 05% fee 04bre				
Descendition	For all reliability	J-STD-020	1.) Baking at 85°C for 24hrs				
Precondition	monitoring tests according		2.) Moisture storage at 85°C/ 60% R.H. for				
	to JEDEC Level 2		168hrs				
0.1.1	1Q/ 1/ 22/ 0	JESD22-B102-B	Accelerated aging 155°C/ 24hrs				
Solderability		And CNS-5068	Tinning speed: 2.5+0.5cm/s				
		0.10.5005	Tinning: A: 215°C/ 3+1s or B: 260°C/ 10+1s				
		CNS-5067	Dipping soldering terminal only				
Resistance to			Soldering bath temperature				
soldering heat			A: 260+/-5°C; 10+/-1s				
			B: 350+/-10°C; 3+/-0.5s				
	1Q/ 1/ 40/ 0	CNS-11829	1.) Precondition: 85°C baking for 24hrs				
Operating life test			85°C/ 60%R.H. for 168hrs				
			2.) Tamb25°C; IF=20mA; duration 1000hrs				
High humidity,	1Q/ 1/ 45/ 0	JESD-A101-B	Tamb: 85°C				
high temperature			Humidity: 85% R.H., IF=5mA				
bias			Duration: 1000hrs				
High temperature	1Q/ 1/ 20	IN specs.	Tamb: 55°C				
bias			IF=20mA				
DIAS			Duration: 1000hrs				
	1Q/ 1/ 40/ 0		Tamb25°C, If=20mA,, Ip=100mA, Duty				
Pulse life test			cycle=0.125 (tp=125µs,T=1sec)				
			Duration 500hrs)				
	1Q/ 1/ 76/ 0	JESD-A104-A	A cycle: -40 degree C 15min; +85 degree C				
Tomporatura		IEC 68-2-14, Nb	15min				
Temperature			Thermal steady within 5 min				
cycle			300 cycles				
			2 chamber/ Air-to-air type				
High humidity	1Q/ 1/ 40/ 0	CNS-6117	60+3°C				
storage test			90+5/-10% R.H. for 500hrs				
High temperature	1Q/ 1/ 40/ 0	CNS-554	100+10°C for 500hrs				
storage test							
Low temperature	1Q/ 1/ 40/ 0	CNS-6118	-40+5°C for 500hrs				
storage test							



Revision History

Changes since last revision	Page	Version No.	Revision Date
Initial Release		1.0	01-27-2021

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